



Thyristor Module

Features

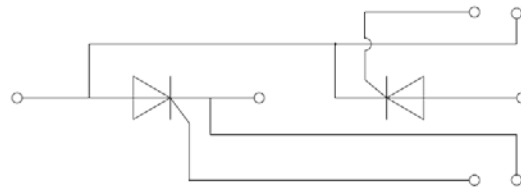
- Half-bridge SCR configuration integrated in a single package
- High-thermal-conductivity DBC insulation for excellent heat dissipation
- Vacuum soldering technology for enhanced reliability

Product Summary

Parameter	Value	Unit
V_{RRM}	2200	V
$I_{T(AV)}$ (@ $T_C = 85^\circ\text{C}$)	160	A
I_{TSM} (@ $t_p = 10\text{ms}$)	3200	A
$V_T(\text{Max})$	1.80	V

Applications

- Heating control
- Light control system
- DC motor



Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Conditions	Symbol	Values	Unit
Repetitive peak off-state voltage	$T_{vj} = 25^\circ\text{C}$	V_{DRM}	2200	V
Repetitive peak reverse voltage	$T_{vj} = 25^\circ\text{C}$	V_{RRM}	2200	V
Non-repetitive peak off-state voltage	$T_{vj} = 25^\circ\text{C}$	V_{DSM}	2300	V
Non-repetitive peak reverse voltage	$T_{vj} = 25^\circ\text{C}$	V_{RSM}	2300	V
Average forward current	$T_C = 85^\circ\text{C}$	$I_{T(AV)}$	160	A
Forward surge current	1/2 cycle, Sine wave, 50Hz $T_{vj} = 25^\circ\text{C}$	I_{TSM}	3200	A
I^2t value for fusing		I^2t	51200	A^2s
Critical rate of rise of on-state current	$I_G=2 \times I_{GT}$	di/dt	150	$\text{A}/\mu\text{s}$
RMS isolation voltage	A.C 50Hz(1s/1min)	V_{ISO}	3600/3000	V
Junction temperature range		T_J	-40 ~ +125	$^\circ\text{C}$
Storage temperature range		T_{stg}	-40 ~ +125	$^\circ\text{C}$

**Electrical Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)**

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Peak forward voltage	$I_T=480\text{A}$, $t_P=380\mu\text{s}$	V_T			1.80	V
Repetitive peak off-state current	$V_D = V_{\text{DRM}}$, $T_{vj} = 25^\circ\text{C}$	I_{DRM}			100	μA
	$V_D = V_{\text{DRM}}$, $T_{vj} = 125^\circ\text{C}$				60	mA
Reverse leakage current	$V_R = V_{\text{RRM}}$, $T_{vj} = 25^\circ\text{C}$	I_{RRM}			100	μA
	$V_R = V_{\text{RRM}}$, $T_{vj} = 125^\circ\text{C}$				60	mA
Threshold voltage	For power loss calculation only $T_{vj} = 125^\circ\text{C}$,	V_{TO}			0.88	V
Dynamic resistance	$T_{vj} = 125^\circ\text{C}$,	r_T			1.55	$\text{m}\Omega$
Triggering gate current	$V_D=12\text{V}$ $R_L=30\Omega$	I_{GT}	20		120	mA
Holding current	$I_T=1\text{A}$	I_H			250	mA
Latching current	$I_G=1.2 I_{\text{GT}}$	I_L			300	mA
Critical rate of rise of voltage	$V_D=2/3V_{\text{DRM}}$ $T_{vj}=125^\circ\text{C}$ Gate Open	dv/dt	1000			$\text{V}/\mu\text{s}$
Triggering gate voltage	$V_D=12\text{V}$ $R_L=30\Omega$	V_{GT}			1.8	V
Non triggering gate voltage	$V_D=0.5V_{\text{DRM}}$ $T_{vj}=125^\circ\text{C}$	V_{GD}	0.25			V

Thermal Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Thermal resistance, junction to case	per chip	$R_{\text{th(j-c)}}$		0.17		$^\circ\text{C}/\text{W}$
Thermal resistance, case to heatsink	per chip	$R_{\text{th(c-s)}}$		0.09		$^\circ\text{C}/\text{W}$
Mounting torque	Module and heatsink fixed torque M5	M	4.25		5.75	N·m
	Electrode connection torque M6		4.25		5.75	N·m



Ordering Information

Device	Marking	Package	Weight	Inner Box	Pre Carton
JMT160KT22T2	JMT160KT22T2	T2	170±10g	6 PCS	72 PCS

Typical Electrical & Thermal Characteristics

FIG.1: Power dissipation vs. on-state current (per thyristor or diode)

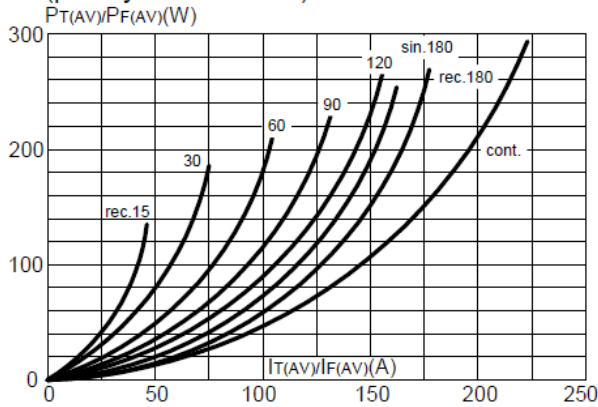


FIG.2: Maximum transient thermal impedance junction to case(per thyristor or diode)

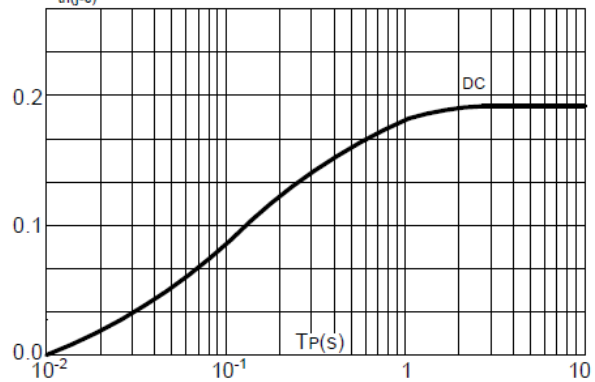


FIG.3: Forward characteristics (per thyristor or diode)

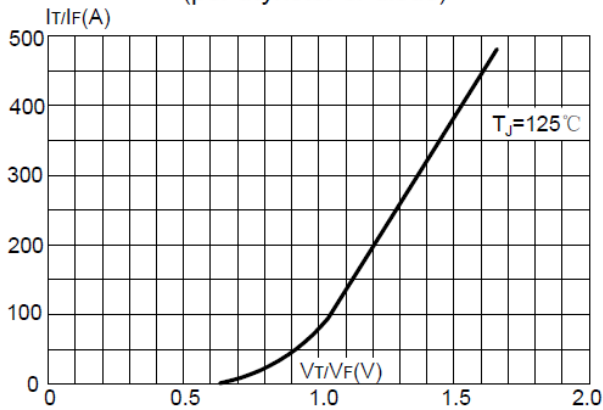
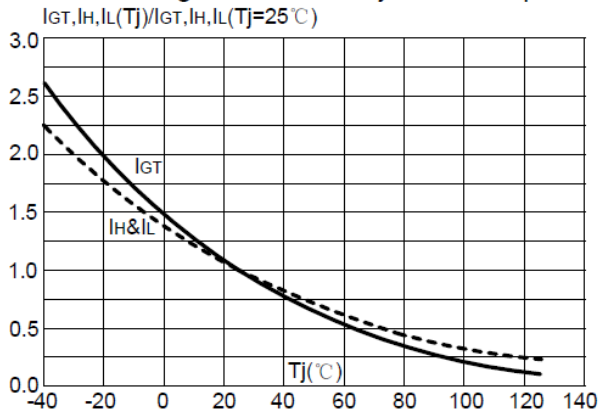
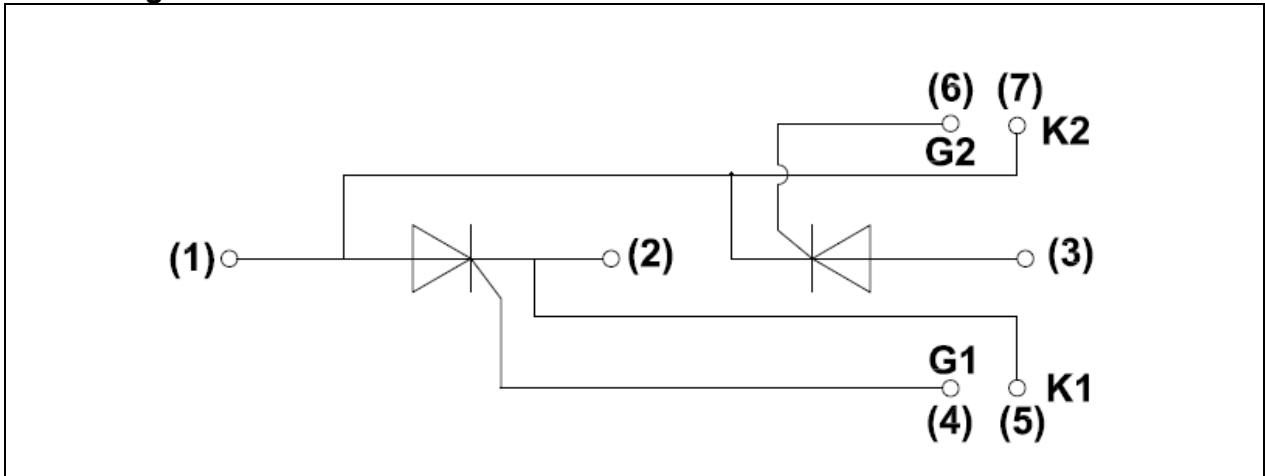


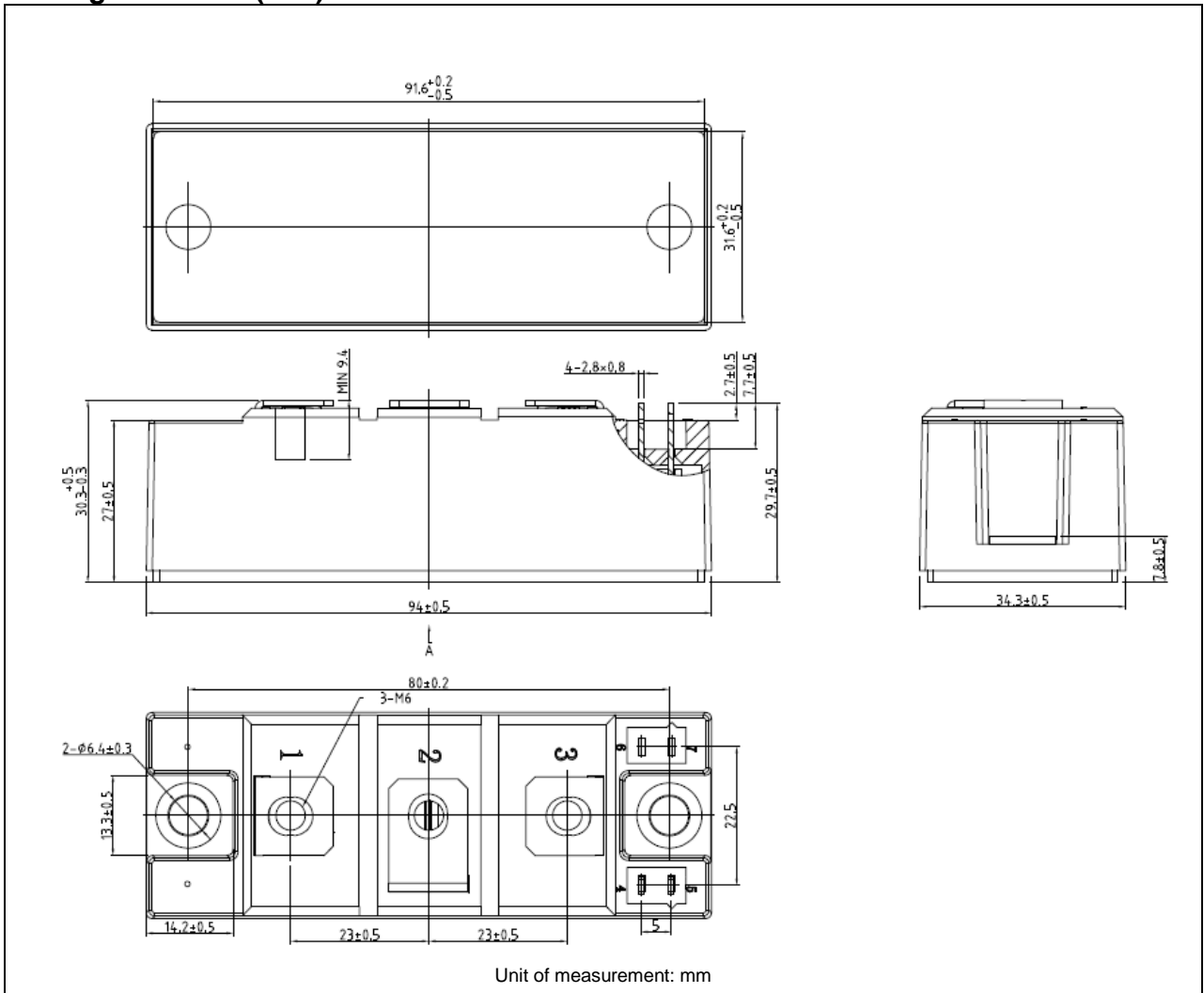
FIG.4: Relative variations of gate trigger current, holding current and latching current versus junction temperature



Circuit Diagram




Package Outlines (mm)





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